

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jon M. Huppenthal and D. James Guzy

Serial No. -----

Filed: Herewith

For: RECONFIGURABLE PROCESSOR
MODULE COMPRISING HYBRID STACKED
INTEGRATED CIRCUIT DIE ELEMENTS

Confirmation No.:

Group Art Unit:

Examiner:

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:


Pursuant to 37 C.F.R. § 1.97, the Examiner may wish to consider the references listed on the attached Form PTO/SB/08A. In submitting these references, no representation is made or implied that the references are or are not material to the examination of this application. Pursuant to 37 C.F.R. 1.98(d), copies of the references are not enclosed, as each reference was either provided or cited in U.S. Serial No. 10/452,113, from which priority under 35 U.S.C. 120 is claimed.

This Information Disclosure Statement is filed before mailing of a first Office Action in the above case. Accordingly, no fee is believed due. However, any fee associated herewith may be charged to Deposit Account No. 50-1123.

3/15/04

Date

Respectfully submitted,



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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>			Application Number	-----	
			Filing Date	Herewith	
			First Named Inventor	Jon M. Huppenthal et al.	
			Art Unit		
			Examiner Name		
Sheet	1	of	2	Attorney Docket No.	ARB001 CON/CIP

U.S. PATENT DOCUMENTS						
Examiner Initials	Cite No. ¹	Document No. No. – Kind Code ²	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Doc	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
		US-6,449,170	09/2002	Nguyen et al.		
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		US-6,092,174	07/18/2000	Roussakov	Entire document	
		US-5,585,675	12/17/1996	Knopf	Entire document	
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		US-6,072,233	06/06/2000	Corisis et al.		
		US-6,451,626	09/17/2002	Lin		
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FOREIGN PATENT DOCUMENTS						
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				Examiner Name	
Sheet	2	of	2	Attorney Docket No.	ARB001 CON/CIP

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s) publisher, city and/or country where published	T ²
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